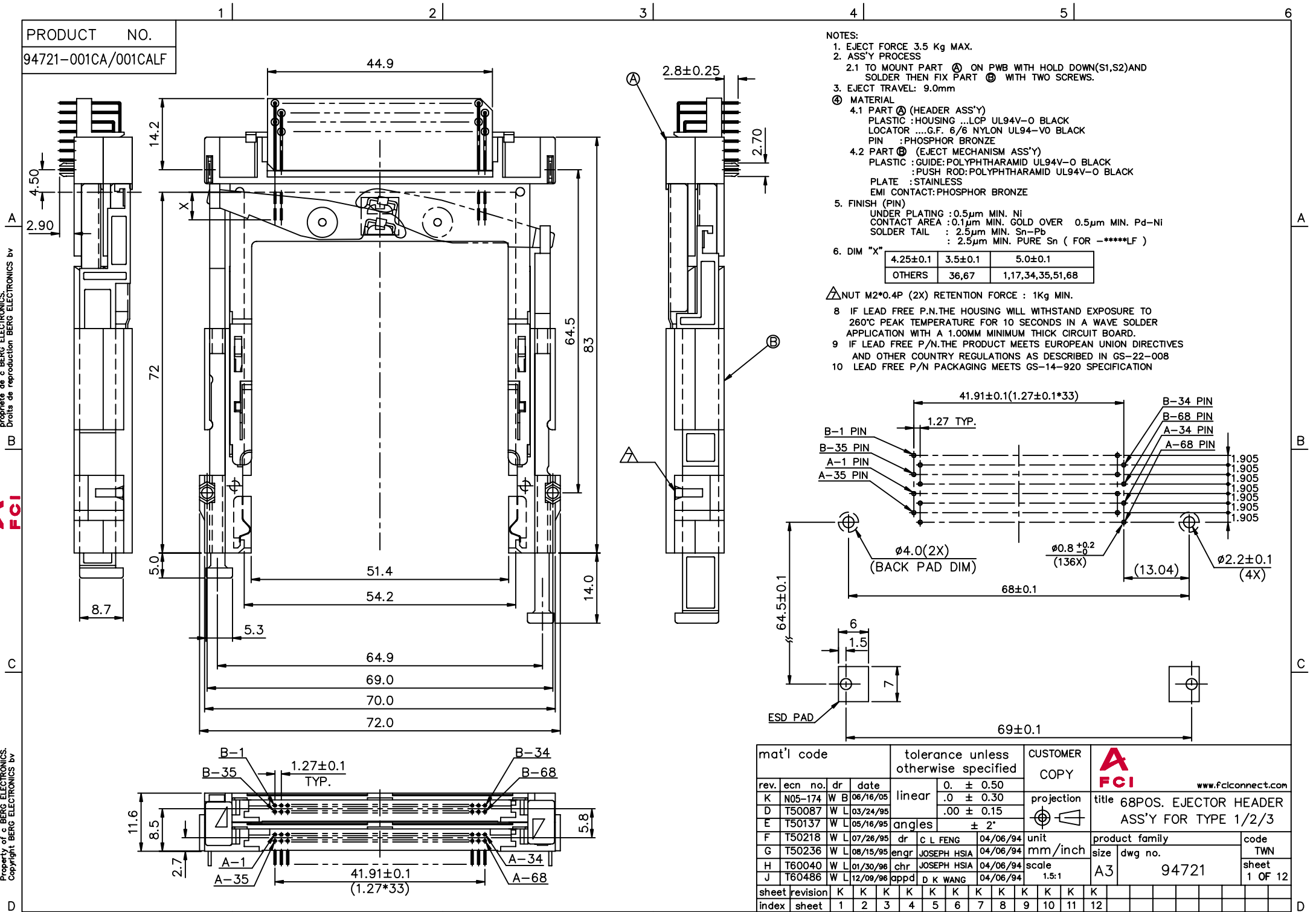


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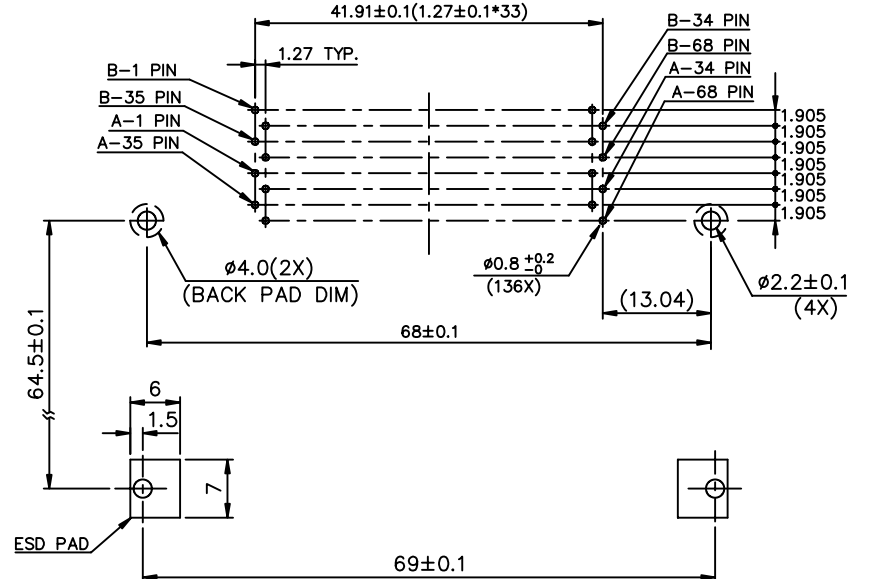
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PRODUCT NO.  
 94721-001CA/001CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
 LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
 PIN : PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
 PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
 : PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
 PLATE : STAINLESS  
 EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)  
 UNDER PLATING : 0.5µm MIN. Ni  
 CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
 SOLDER TAIL : 2.5µm MIN. Sn-Pb  
 : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )
  - DIM "X"
 

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- △ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



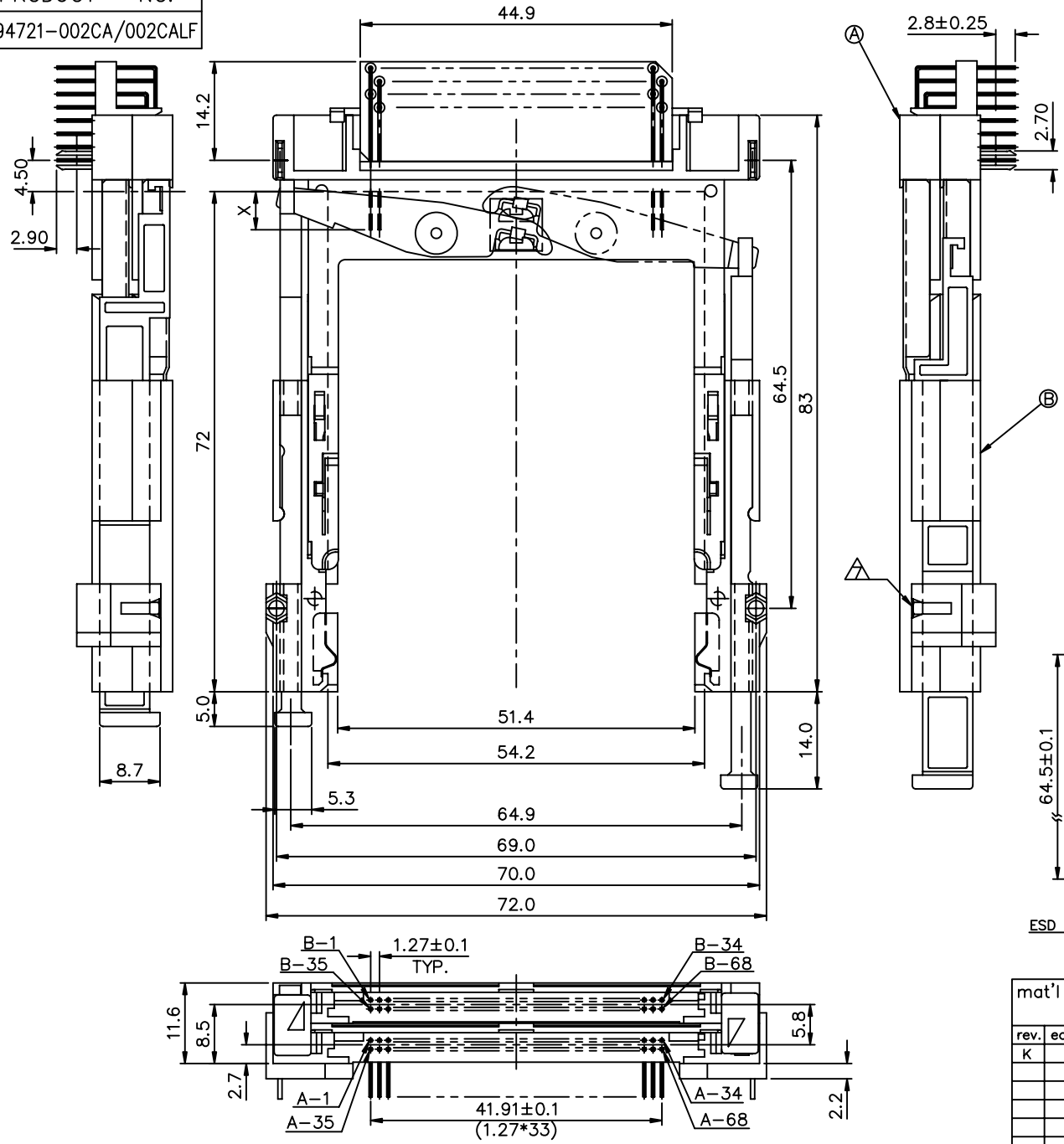
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K	N05-174	W B	06/16/05		.0 ± 0.30	⊕	product family						
D	T50087	W L	03/24/95	angles	.00 ± 0.15		size						
E	T50137	W L	05/16/95		± 2'	dwg no.							
F	T50218	W L	07/26/95	dr	c L FENG	04/06/94	product family		code				
G	T50236	W L	08/15/95	enr	JOSEPH HSIA	04/06/94	size		TWN				
H	T60040	W L	01/30/96	chr	JOSEPH HSIA	04/06/94	scale		sheet				
J	T60486	W L	12/09/96	appd	D K WANG	04/06/94	1.5:1		1 OF 12				
sheet revision													
index	sheet	1	2	3	4	5	6	7	8	9	10	11	12

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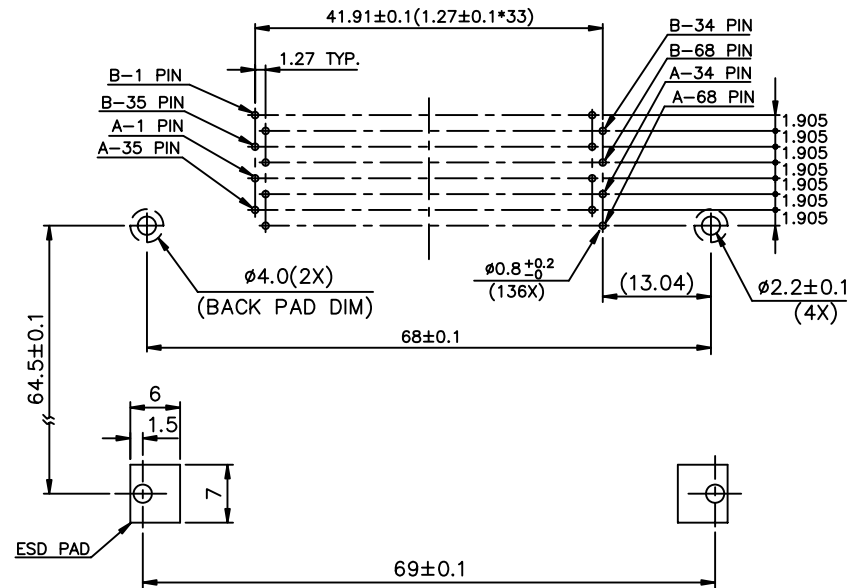
PRODUCT NO.  
94721-002CA/002CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
PLASTIC :HOUSING ...LCP UL94V-0 BLACK  
LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
PIN :PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
PLASTIC :GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
:PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
PLATE :STAINLESS  
EMI CONTACT:PHOSPHOR BRONZE
  - FINISH (PIN)  
UNDER PLATING :0.5µm MIN. Ni  
CONTACT AREA :0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
SOLDER TAIL : 2.5µm MIN. Sn-Pb  
: 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

- ⊕ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



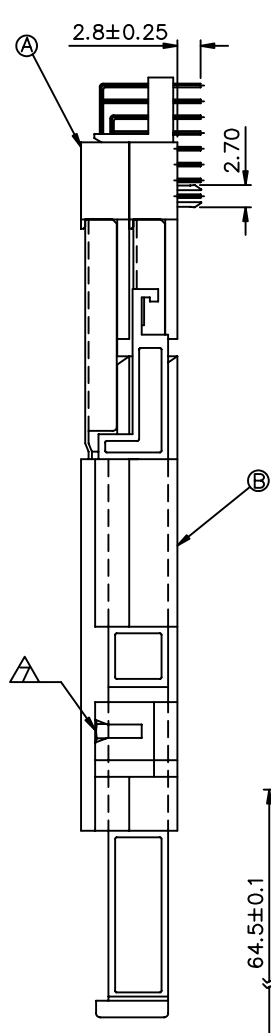
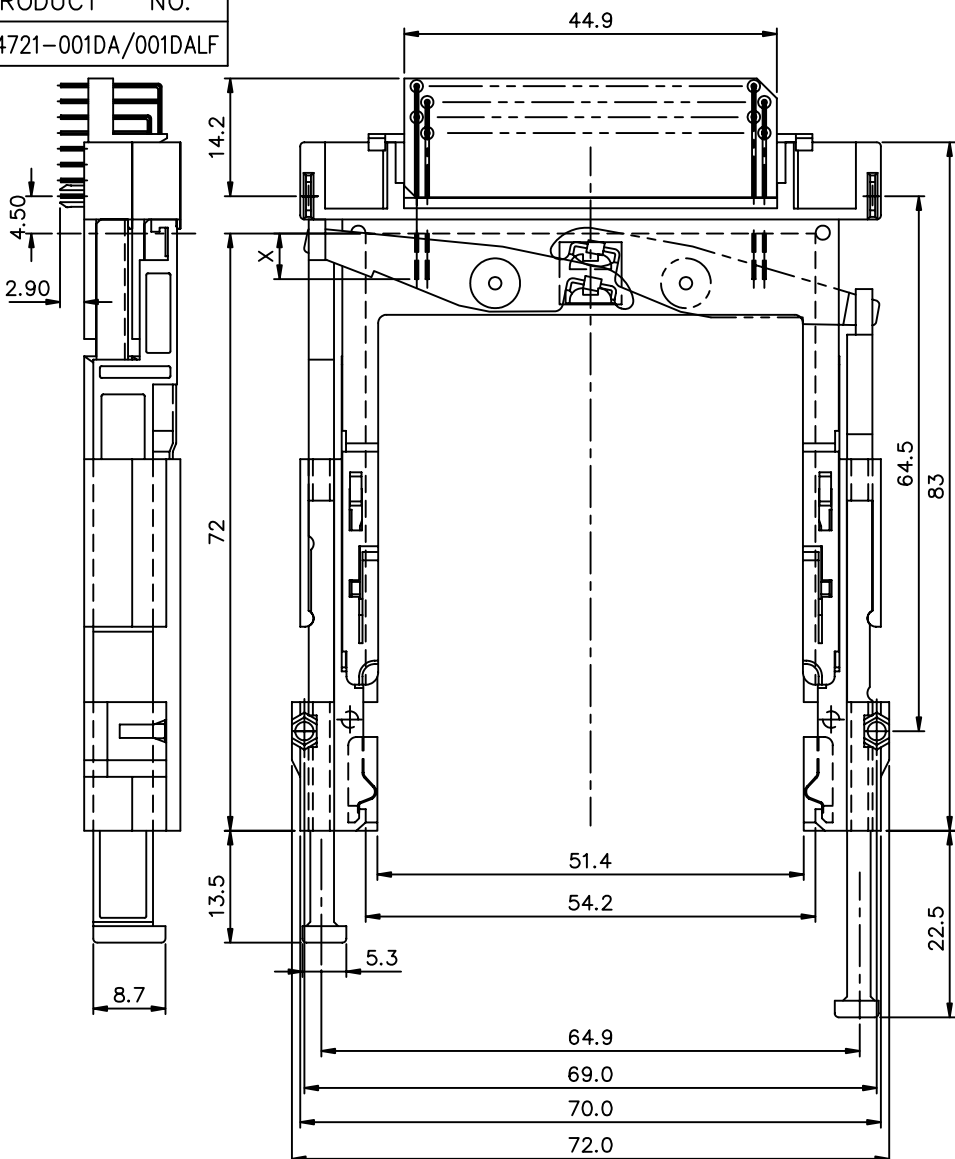
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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K					.0 ± 0.30	⊕	product family		code
				angles	.00 ± 0.15		size		TWN
				dr	± 2'	unit	dwg no.		sheet
				engr		mm/inch	94721		2 OF
				chr		scale			
				appd		1.5:1			
sheet	revision								
index	sheet								

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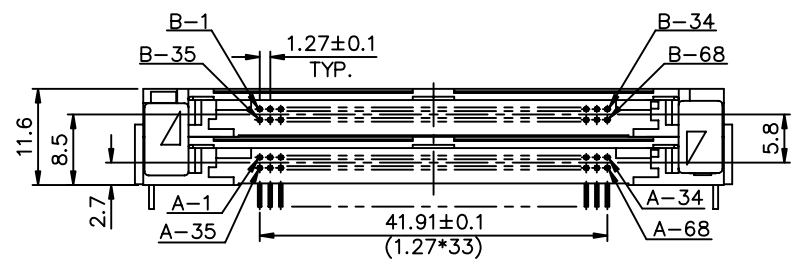
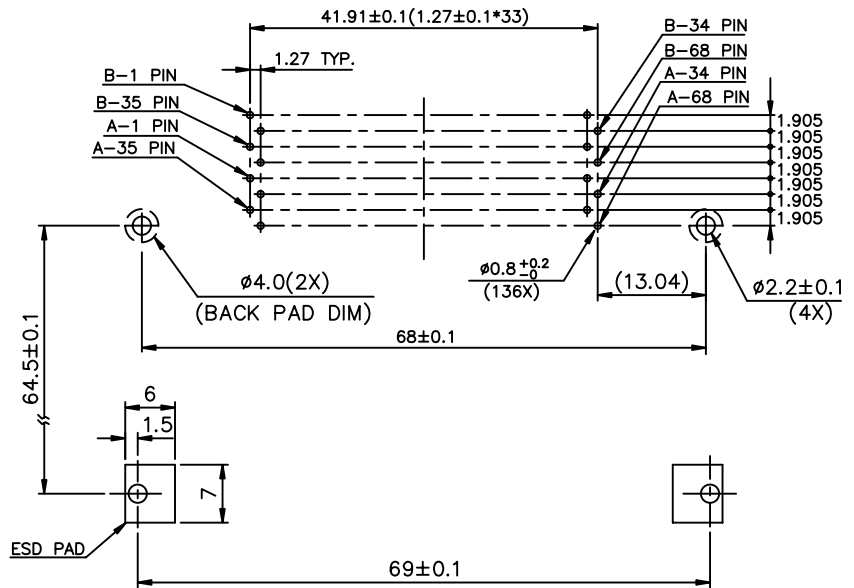
PRODUCT NO.  
94721-001DA/001DALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
  - 4.1 PART (A) (HEADER ASS'Y)  
PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
PIN : PHOSPHOR BRONZE
  - 4.2 PART (B) (EJECT MECHANISM ASS'Y)  
PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
: PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
PLATE : STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)  
UNDER PLATING : 0.5µm MIN. Ni  
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
SOLDER TAIL : 2.5µm MIN. Sn-Pb  
: 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*LF )
6. DIM "X"
 

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- △NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
K				.0 ± 0.30		product family	
				.00 ± 0.15			
				angles	± 2'	unit	TWN
		dr	CATHY LIN	06/16/94	mm/inch	size	dwg no.
		enrg	JOSEPH HSIA	06/16/94	scale	A3	94721
		chr	JOSEPH HSIA	06/16/94	1.5:1		sheet 3 OF
		appd	D K WANG	06/16/94			
sheet index	revision sheet						



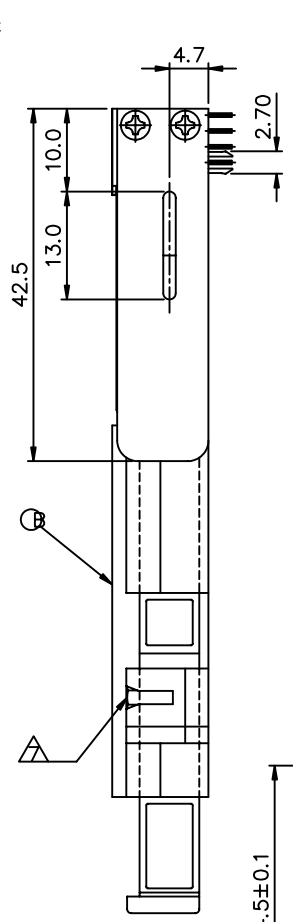
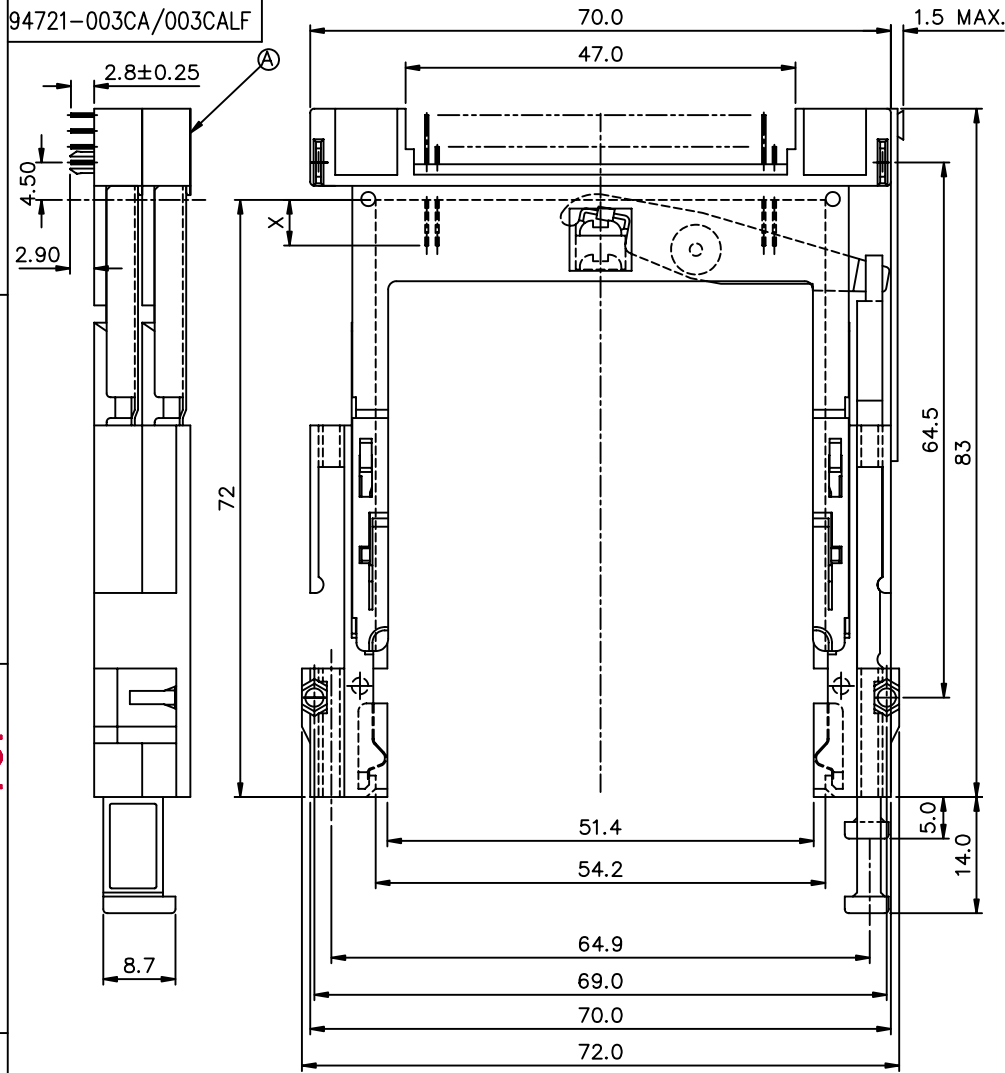
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PRODUCT NO.  
 94721-003CA/003CALF

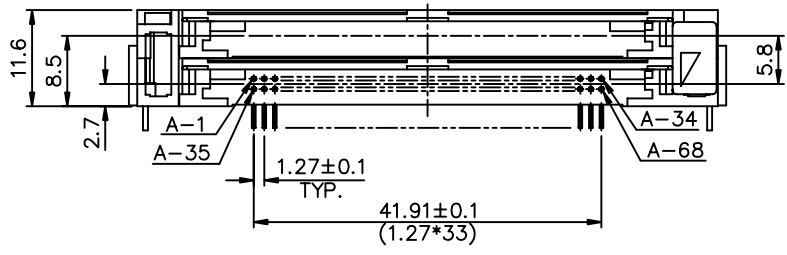
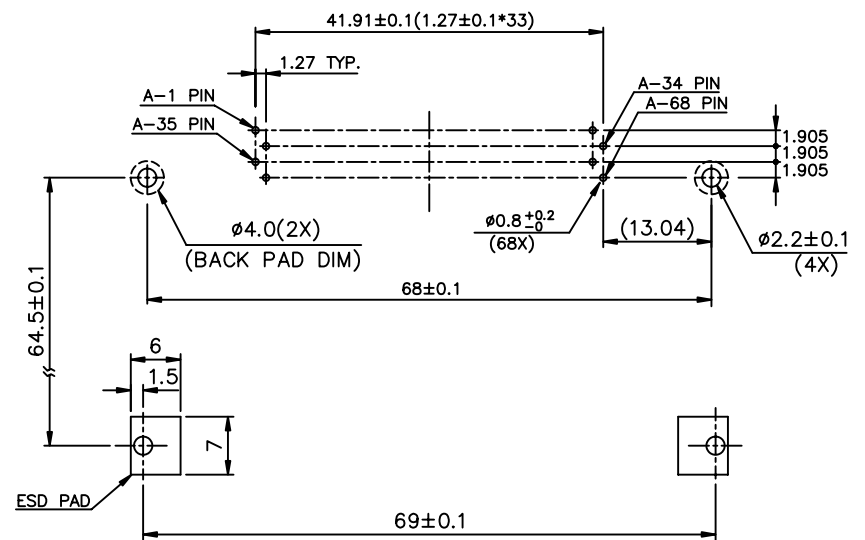
1 | 2 | 3 | 4 | 5 | 6



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART A (HEADER ASS'Y)  
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
 LOCATOR ....G.F. 6/6 NYLON UL94-V0 BLACK  
 PIN : PHOSPHOR BRONZE
    - PART B (EJECT MECHANISM ASS'Y)  
 PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
 : PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
 PLATE : STAINLESS  
 EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)  
 UNDER PLATING : 0.5µm MIN. Ni  
 CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
 SOLDER TAIL : 2.5µm MIN. Sn-Pb  
 : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	

- △ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



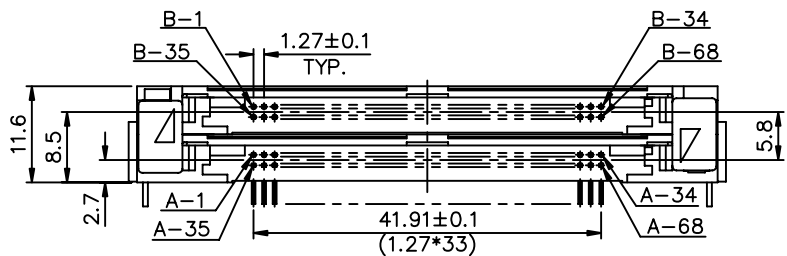
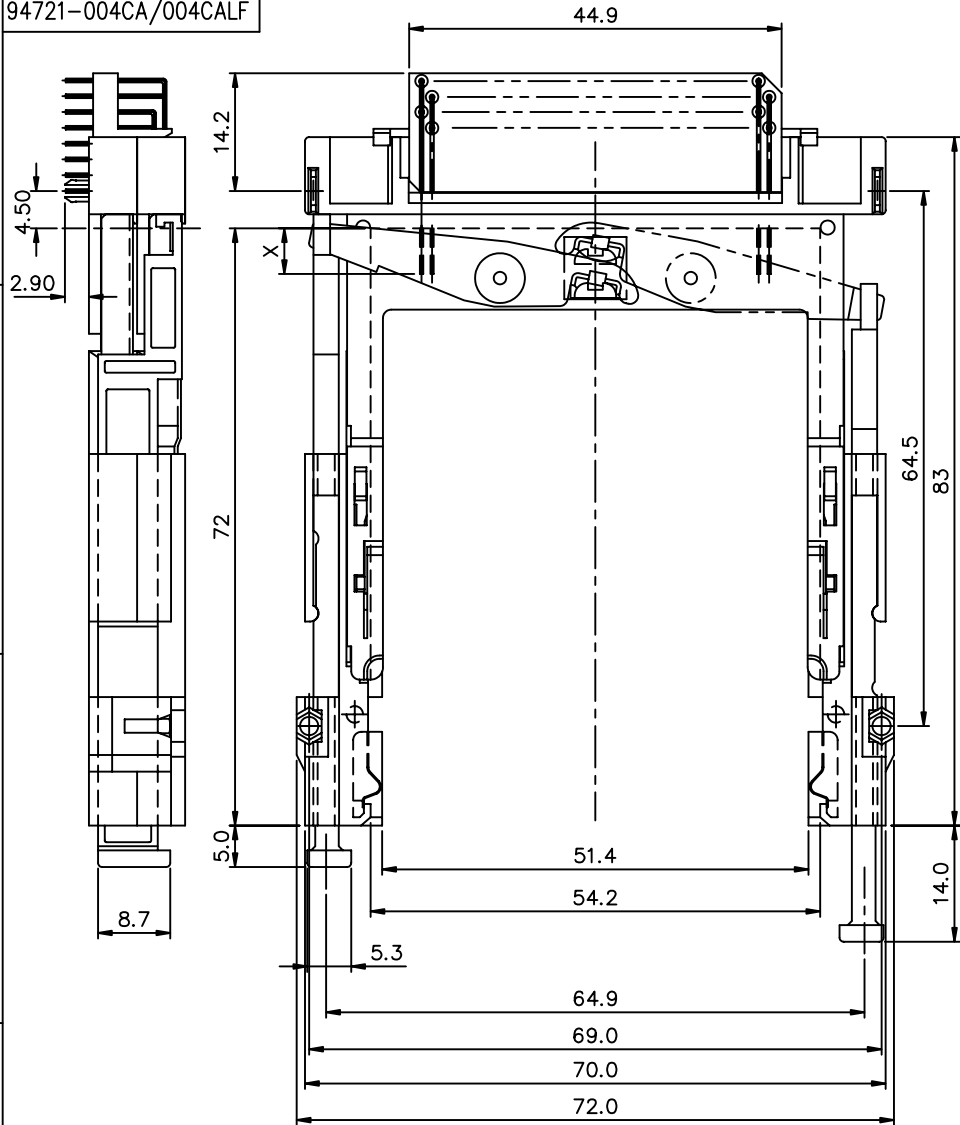
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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K					.0 ± 0.30		product family		code
				angles	.00 ± 0.15		size	dwg no.	TWN
		dr	C L FENG	10/07/94	± 2°	unit	A3	94721	sheet 5 OF
		enr	JOSEPH HSIA	10/07/94		mm/inch			
		chr	JOSEPH HSIA	10/07/94		scale			
		appd	D K WANG	10/07/94		1.5:1			
sheet	revision								
index	sheet								

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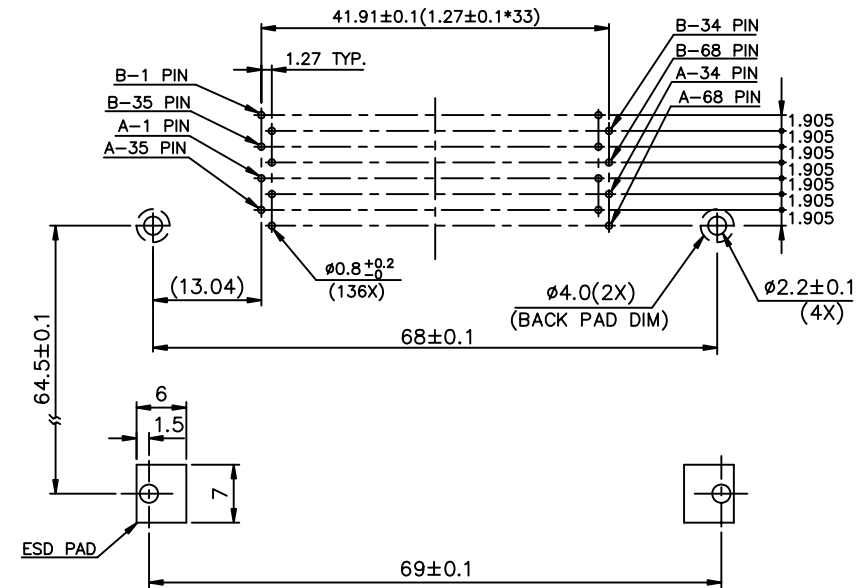
PRODUCT NO.  
94721-004CA/004CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
LOCATOR ....G.F. 6/6 NYLON UL94-V0 BLACK  
PIN : PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
PLATE : STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)  
UNDER PLATING : 0.5µm MIN. Ni  
CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
SOLDER TAIL : 2.5µm MIN. Sn-Pb  
                  : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

- △NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
K				.0 ± 0.30		product family	
				.00 ± 0.15			
				angles	± 2'	unit	TWN
		dr	C L FENG	10/07/94		mm/inch	size
		enrg	JOSEPH HSIA	10/07/94			dwg no.
		chr	JOSEPH HSIA	10/07/94		scale	94721
		appd	D K WANG	10/07/94		1.5:1	sheet 6 OF
sheet	revision						
index	sheet						

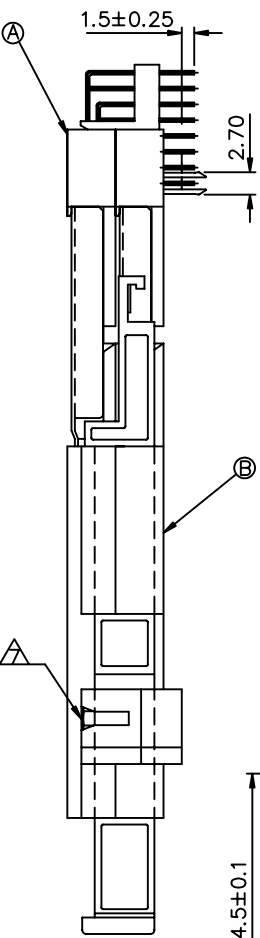
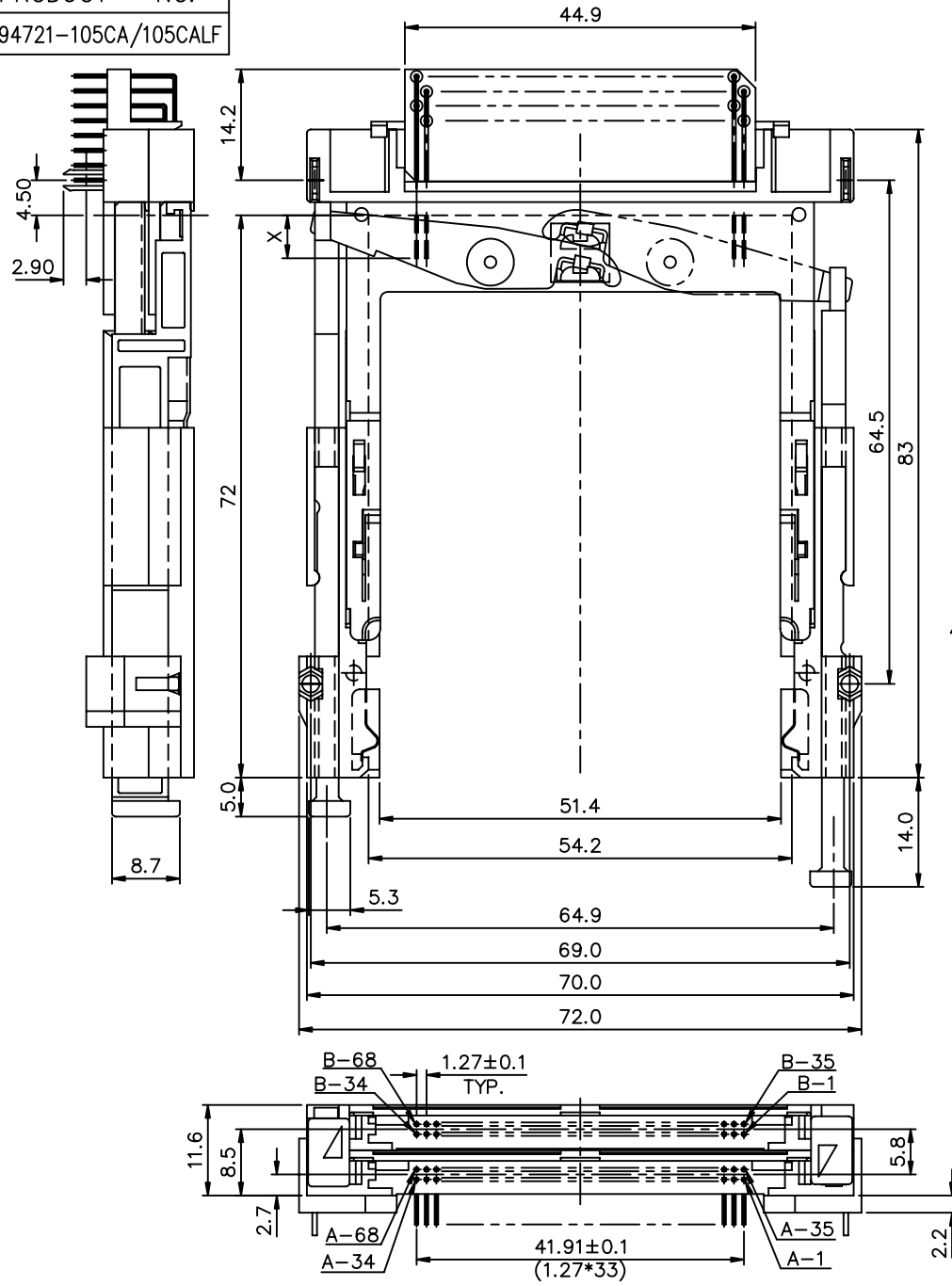


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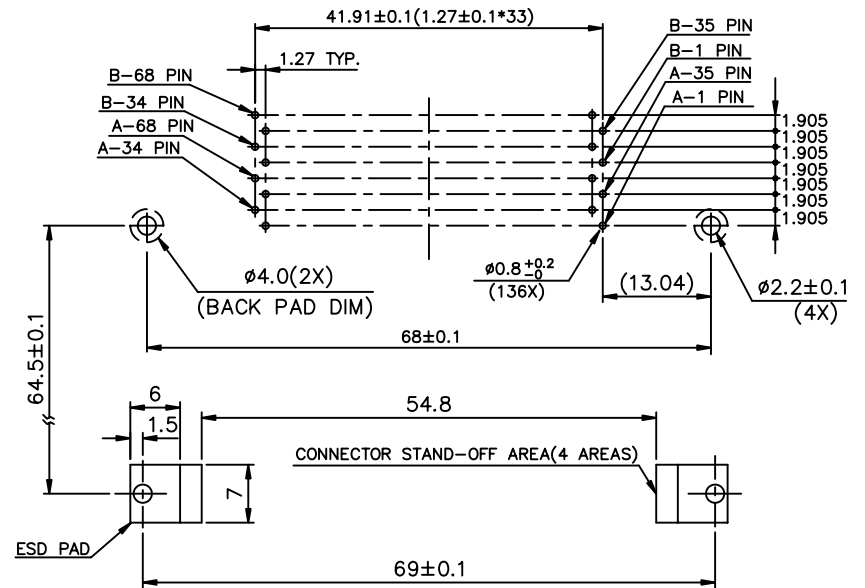
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PRODUCT NO.  
 94721-105CA/105CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
 PLASTIC :HOUSING ...LCP UL94V-O BLACK  
 LOCATOR ....G.F. 6/6 NYLON UL94-VO BLACK  
 PIN :PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
 PLASTIC :GUIDE:POLYPHTHARAMID UL94V-O BLACK  
 :PUSH ROD:POLYPHTHARAMID UL94V-O BLACK  
 PLATE :STAINLESS  
 EMI CONTACT:PHOSPHOR BRONZE
  - FINISH (PIN)  
 UNDER PLATING :0.5µm MIN. Ni  
 CONTACT AREA :0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
 SOLDER TAIL : 2.5µm MIN. Sn-Pb  
 : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )
- |         |          |                  |         |
|---------|----------|------------------|---------|
| DIM "X" | 4.25±0.1 | 3.5±0.1          | 5.0±0.1 |
| OTHERS  | 36,67    | 1,17,34,35,51,68 |         |

- △ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION

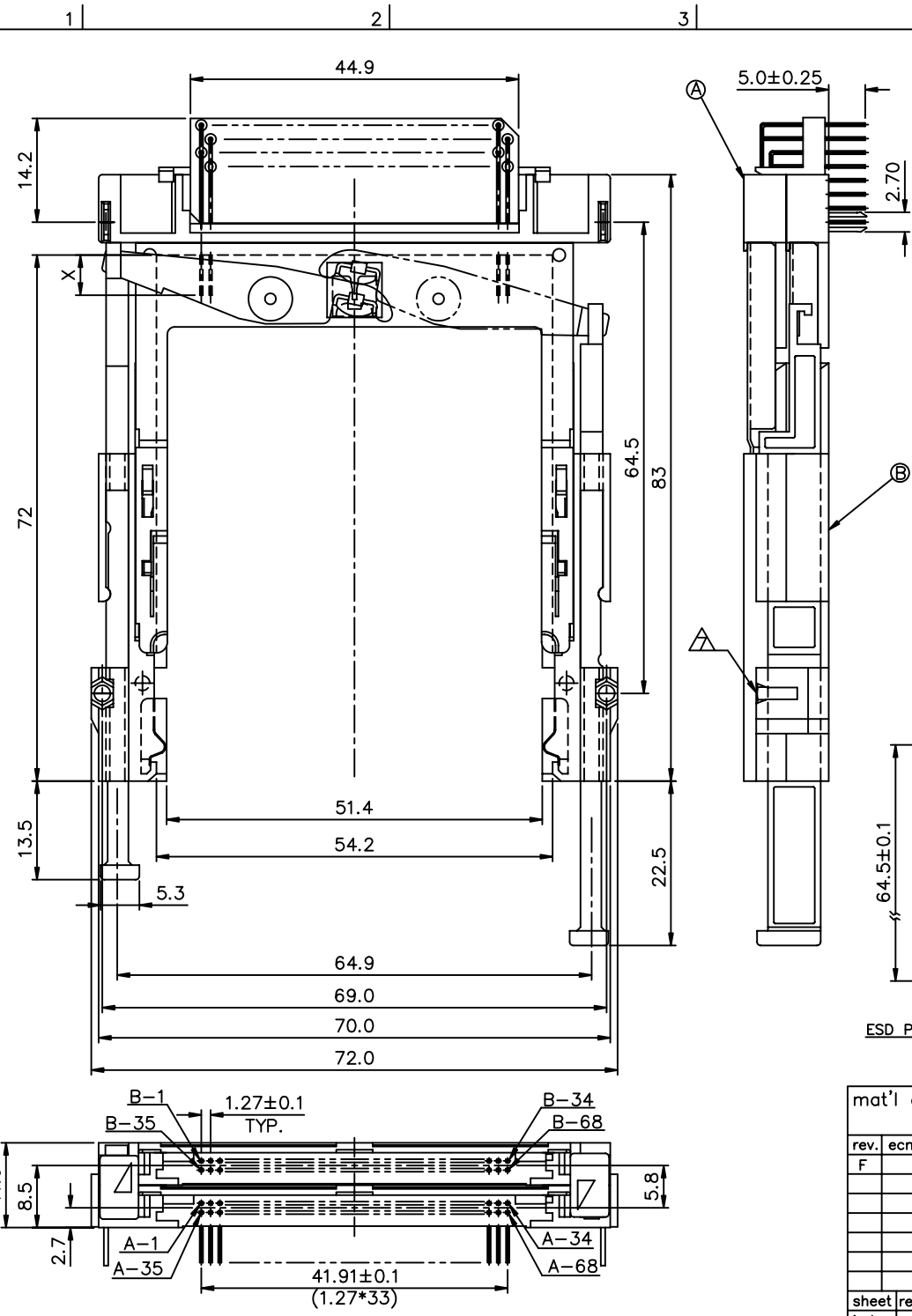


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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3	
K					.0 ± 0.30		product family	
				angles	.00 ± 0.15			size
				dr	± 2'	mm/inch	dwg no.	sheet 7 OF
				engr		scale	94721	
				chr		1.5:1		
				appd				
sheet	revision							
index	sheet							

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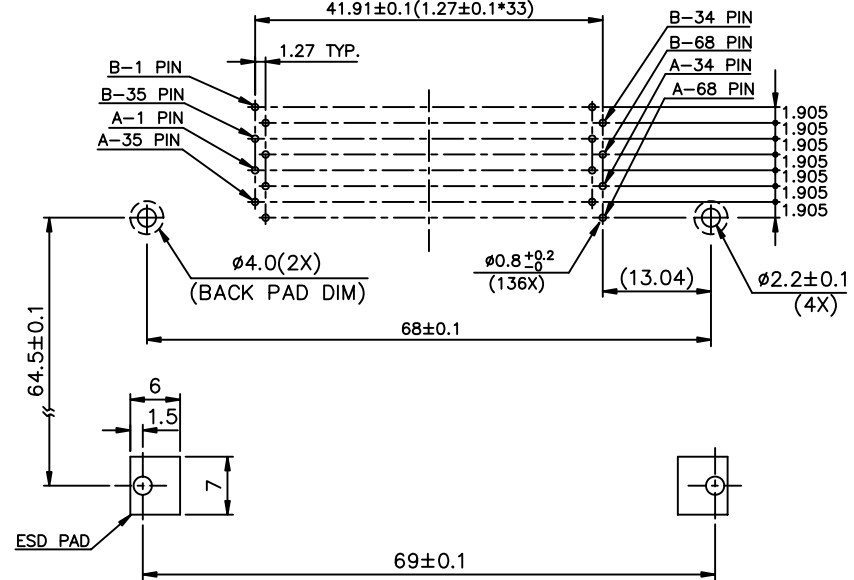
PRODUCT NO.  
 94721-003DA/003DALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
    - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2) AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
 LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
 PIN : PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
 PLASTIC : GUIDE: POLYPHTHAMID UL94V-0 BLACK  
 : PUSH ROD: POLYPHTHAMID UL94V-0 BLACK  
 PLATE : STAINLESS  
 EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)  
 UNDER PLATING : 0.5µm MIN. Ni  
 CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
 SOLDER TAIL : 2.5µm MIN. Sn-Pb  
 : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*LF )

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	

- (A) NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N. THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCI	
rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title
F					.0 ± 0.30		68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
				angles	.00 ± 0.15		product family
					± 2'		code
		dr	WENDY CHEN	03/23/95	unit	mm/inch	TWN
		enr	JOSEPH HSIA	03/23/95	scale	1.5:1	8 OF
		chr	JOSEPH HSIA	03/23/95	size	A3	94721
		appd	D K WANG	03/23/95	sheet		
sheet	revision						
index	sheet						



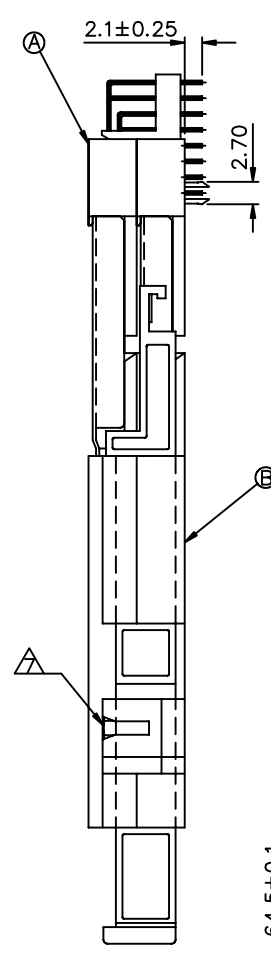
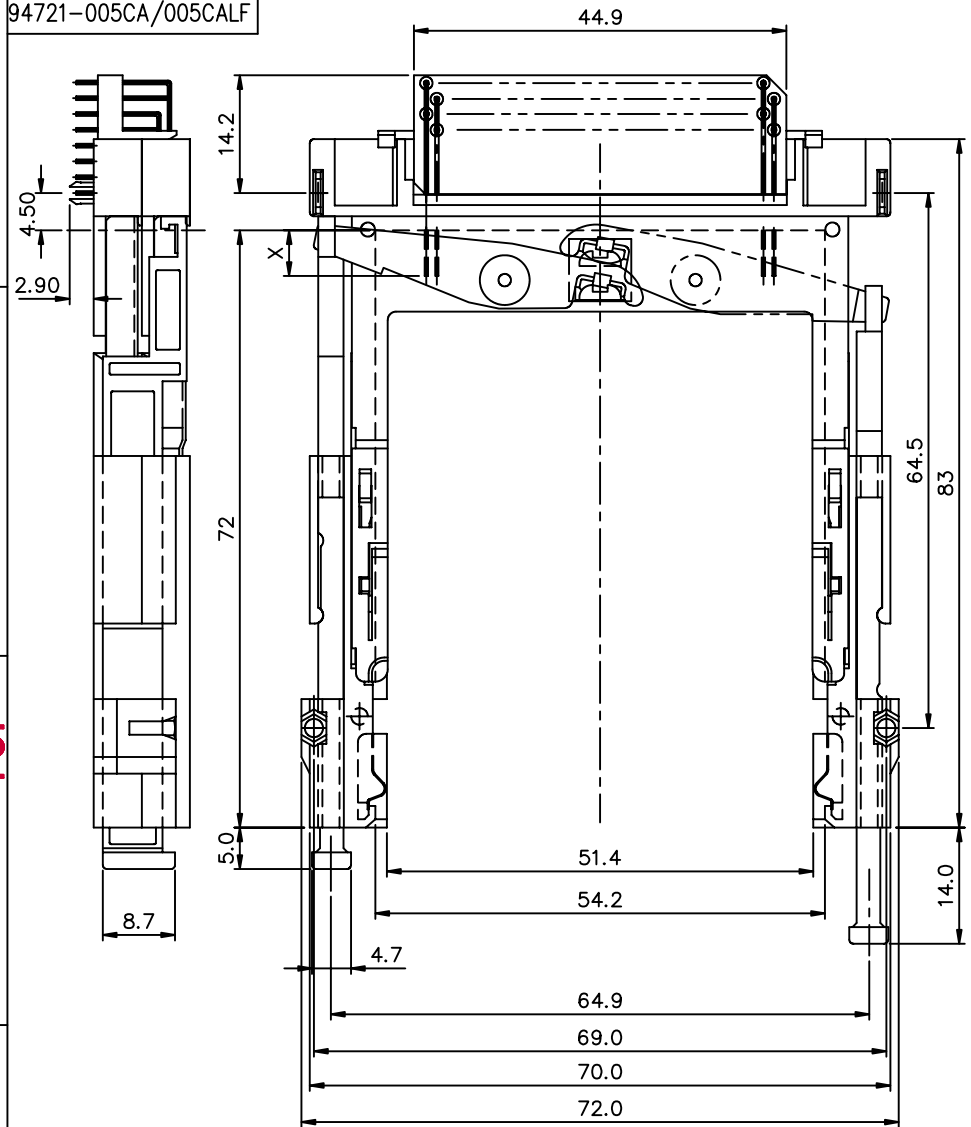
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PRODUCT NO.  
 94721-005CA/005CALF

1 | 2 | 3 | 4 | 5 | 6



NOTES:

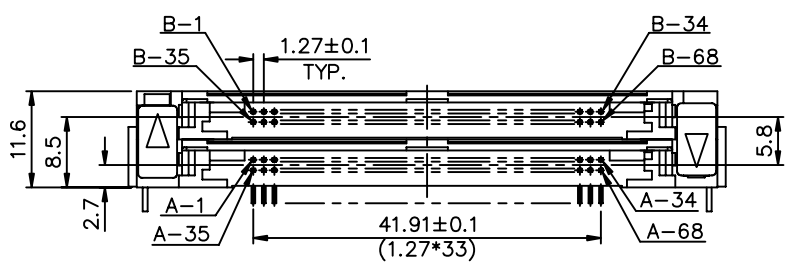
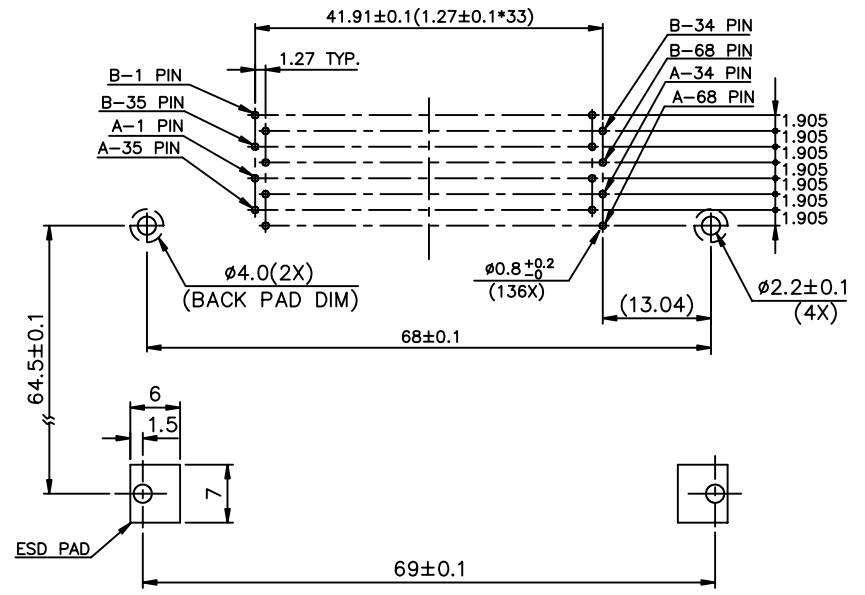
- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
  - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
  - PART (A) (HEADER ASS'Y)  
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
 LOCATOR ....G.F. 6/6 NYLON UL94-V0 BLACK  
 PIN : PHOSPHOR BRONZE
  - PART (B) (EJECT MECHANISM ASS'Y)  
 PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
 PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
 PLATE : STAINLESS  
 EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
 

UNDER PLATING : 0.5µm MIN. Ni	CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
SOLDER TAIL : 2.5µm MIN. Sn-Pb	
	: 2.5µm MIN. PURE Sn ( FOR -*****LF )

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

⚠ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.

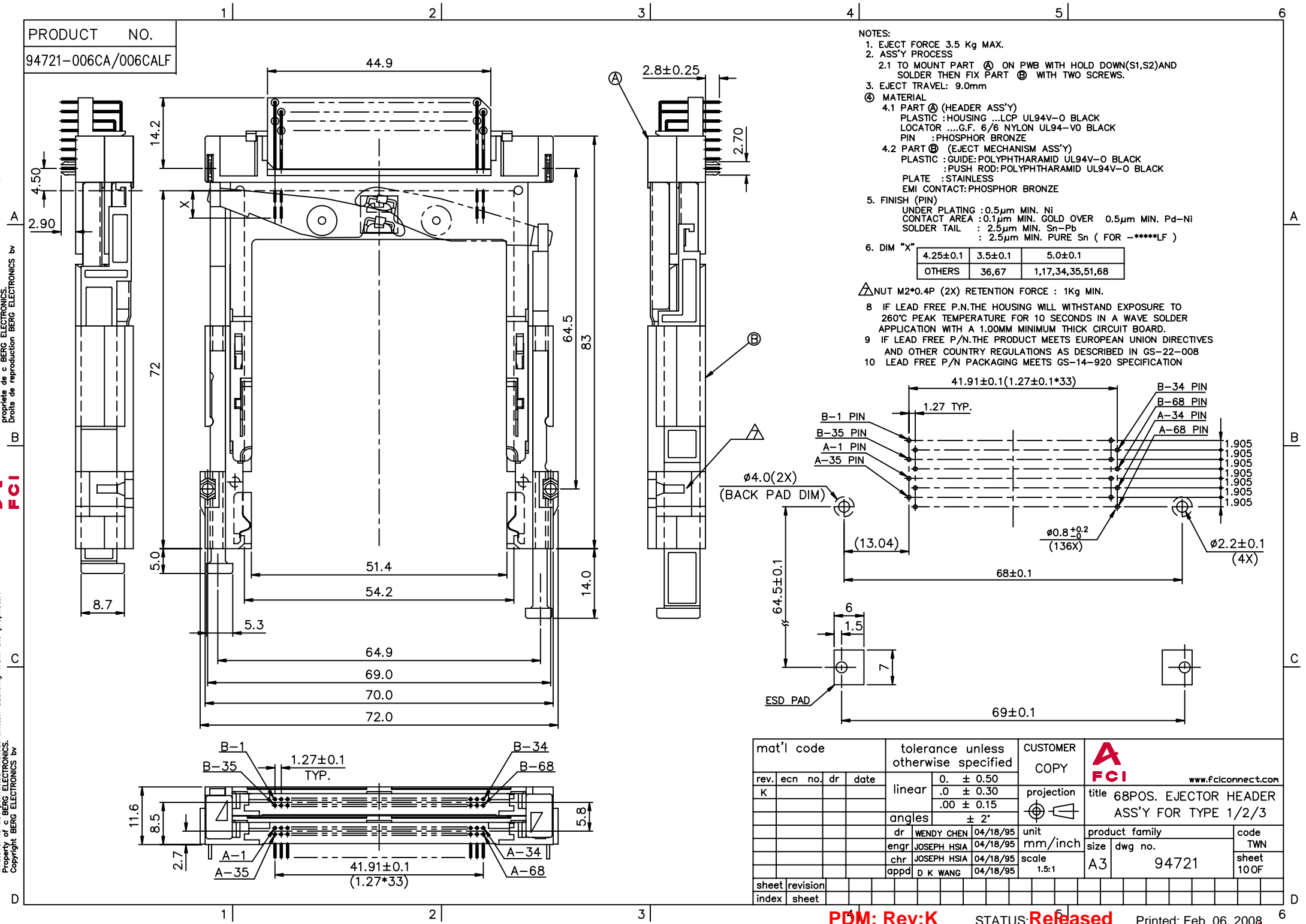
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		<b>FCI</b> www.fclconnect.com	
rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
K				angles	.0 ± 0.30	⊕	
					.00 ± 0.15		product family
		dr	WENDY CHEN	03/25/95	unit	mm/inch	code
		enr	JOSEPH HSIA	03/25/95	scale	1.5:1	TWN
		chr	JOSEPH HSIA	03/25/95	size	A3	94721
		appd	D K WANG	03/25/95	sheet	9 OF	
sheet	revision						
index	sheet						

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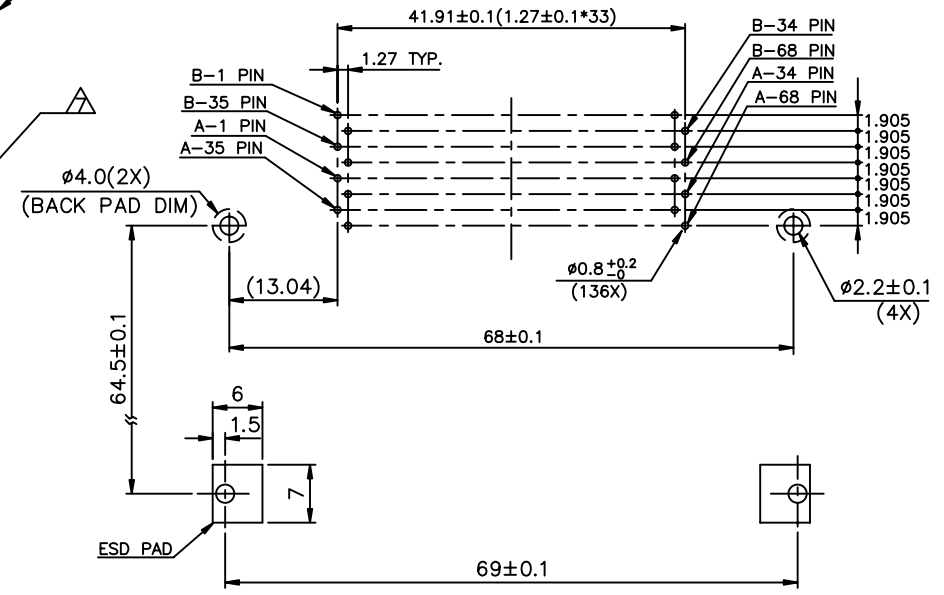
PRODUCT NO.  
94721-006CA/006CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
 PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
 LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
 PIN : PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
 PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
 : PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
 PLATE : STAINLESS  
 EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)  
 UNDER PLATING : 0.5µm MIN. Ni  
 CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni  
 SOLDER TAIL : 2.5µm MIN. Sn-Pb  
 : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

- △NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



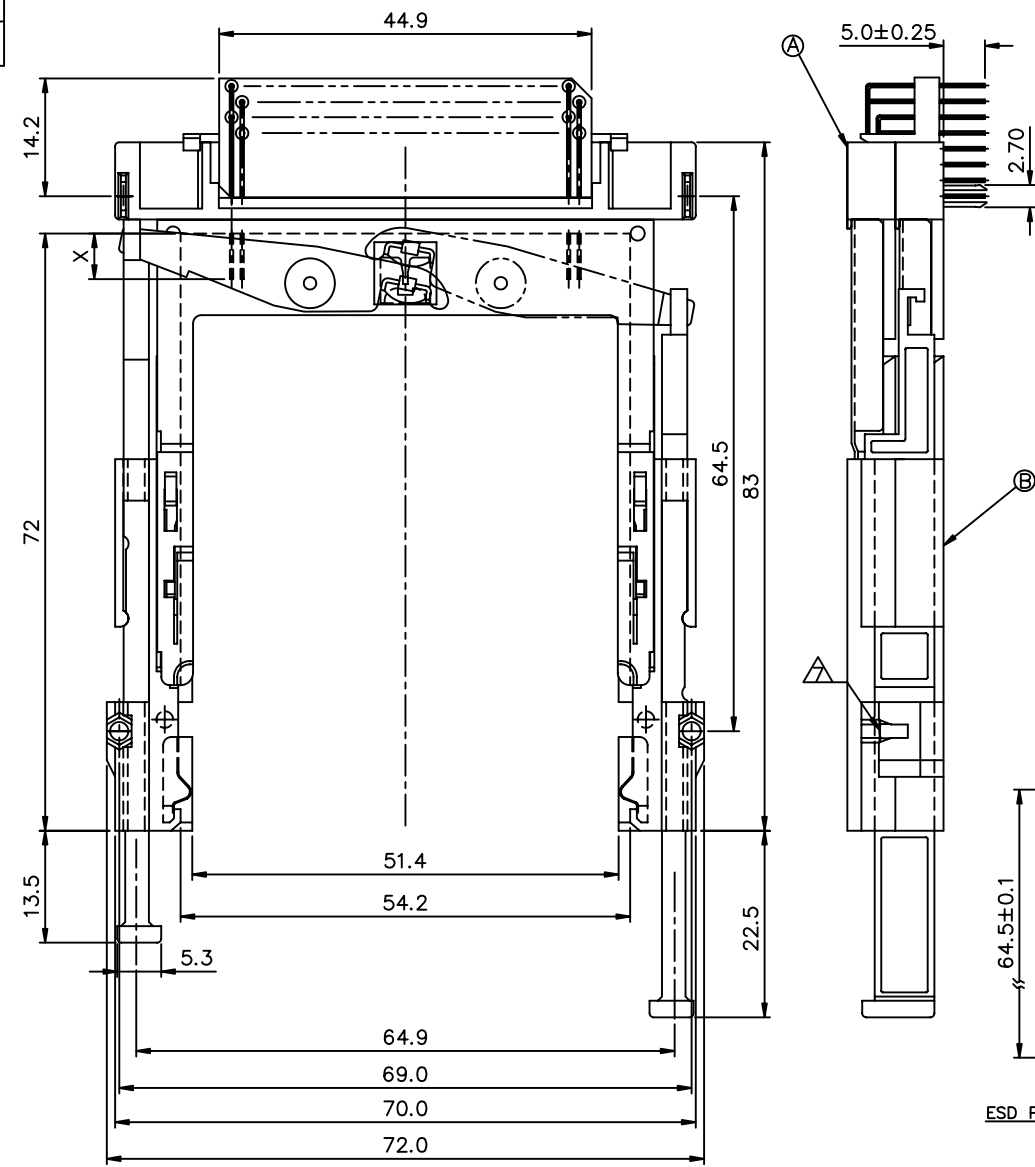
mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCI		www.fclconnect.com	
rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K				angles	.0 ± 0.30		product family		
					.00 ± 0.15		size	code	
		dr	WENDY CHEN	04/18/95	unit	mm/inch	TWN		
		enr	JOSEPH HSIA	04/18/95	scale	1.5:1	sheet		
		chr	JOSEPH HSIA	04/18/95	scale	1.5:1	10OF		
		appd	D K WANG	04/18/95			sheet		
sheet	revision						10OF		
index	sheet						10OF		

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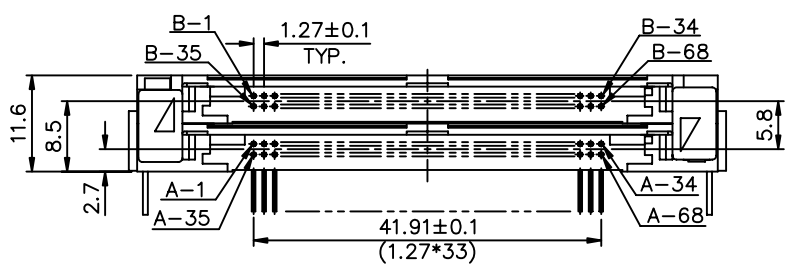
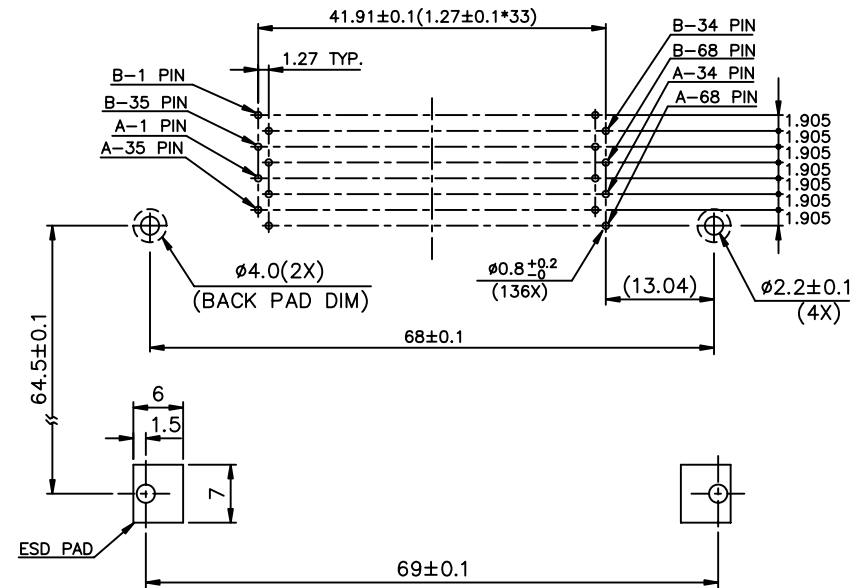
PRODUCT NO.  
94721-004DA/004DALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
  - ASS'Y PROCESS
  - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
  - EJECT TRAVEL: 9.0mm
  - MATERIAL
    - PART (A) (HEADER ASS'Y)  
PLASTIC : HOUSING ...LCP UL94V-0 BLACK  
LOCATOR ...G.F. 6/6 NYLON UL94-V0 BLACK  
PIN : PHOSPHOR BRONZE
    - PART (B) (EJECT MECHANISM ASS'Y)  
PLASTIC : GUIDE: POLYPHTHARAMID UL94V-0 BLACK  
: PUSH ROD: POLYPHTHARAMID UL94V-0 BLACK  
PLATE : STAINLESS  
EMI CONTACT: PHOSPHOR BRONZE
  - FINISH (PIN)
    - UNDER PLATING : 0.5µm MIN. NI
    - CONTACT AREA : 0.1µm MIN. GOLD OVER 0.5µm MIN. Pd-Ni
    - SOLDER TAIL : 2.5µm MIN. Sn-Pb
    - : 2.5µm MIN. PURE Sn ( FOR -\*\*\*\*\*LF )

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68

- △ NUT M2\*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
  - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
  - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



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rev.	ecn no.	dr	date	linear	0. ± 0.50	projection	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K					.0 ± 0.30		product family		
				angles	.00 ± 0.15		code TWN		
					± 2°		size	dwg no.	sheet
		dr	WENDY CHEN	08/15/95	unit	mm/inch	A3	94721	110F
		enr	JOSEPH HSIA	08/15/95	scale	1.5:1			
		chr	JOSEPH HSIA	08/15/95					
		appd	JENN TSAO	08/15/95					
sheet	revision								
index	sheet								

